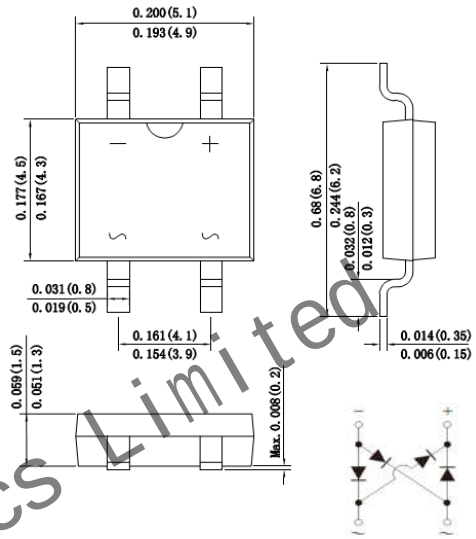
Single Phase 1.0Amp Glass passivated Bridge Rectifiers

ABS

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250℃/10 seconds at terminals



Dimensions in inches and (millimeters)

Mechanical Data

Case : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0034 ounce, 0.098 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ARDAB S2HX0	ARDAB S4HX0	ARDAB S6HX0	ARDAB S8HX0	ARDAB S10HX0	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current at T_L=100℃ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	35.0					A
Rating for fusing (t=8.3ms, Ta=25℃)	I^2t	5.08					A^2s
Maximum instantaneous forward voltage at 1.0A	V_F	1.10					V
Maximum DC reverse current T_A =25℃ at rated DC blocking voltage T_A=125℃	I_R	5.0 500					uA
Typical junction capacitance (Note 2)	C_J	16.0					pF
Typical thermal resistance	$R_{\theta JA}$	80.0					°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150					°C

Note:1.Mounted on glass epoxy PC board with 1.3*1.3mm solder pad
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

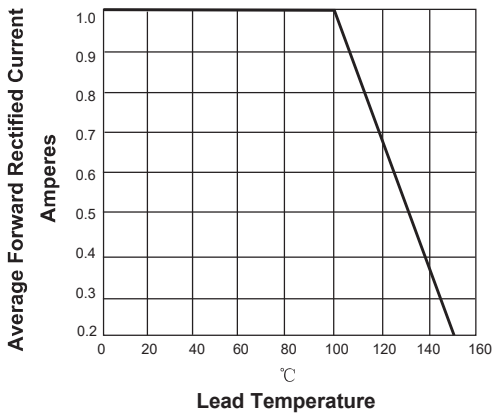


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

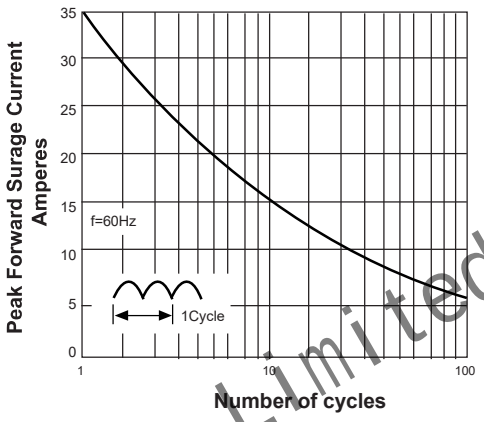


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

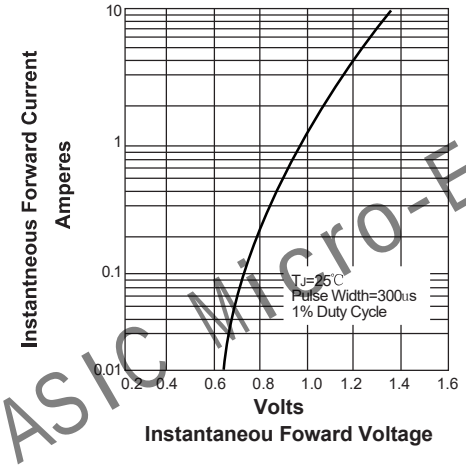
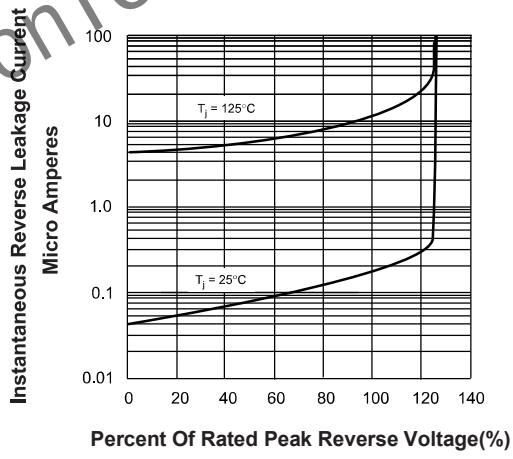
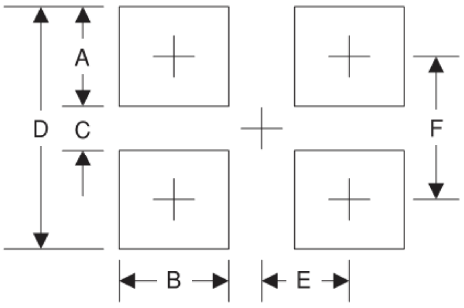


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

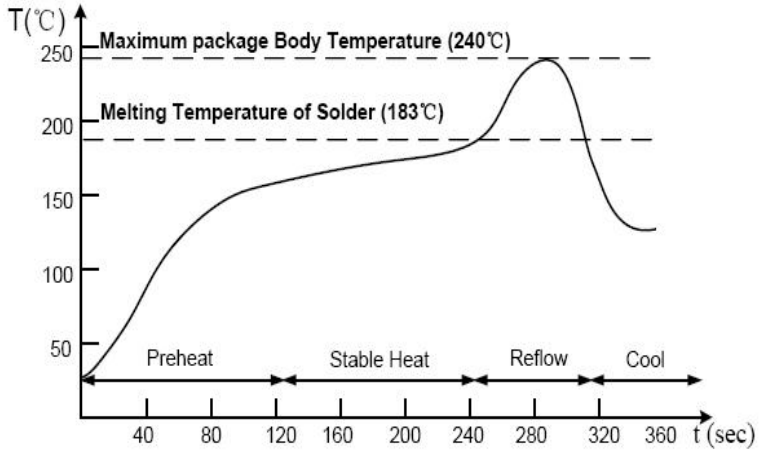


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.5	0.059
B	1.0	0.039
C	4.22	0.166
D	7.22	0.284
E	2.0	0.078
F	5.70	0.224

Suggested Soldering Temperature Profile

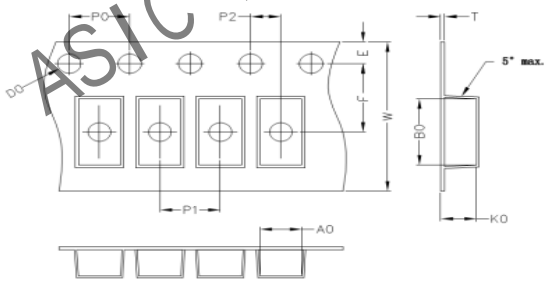


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.31	6.68	1.6	1.55	1.75	5.50
P0	**P1**	**P2**	**T**	**W**	**Tolerance**
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
ABS	11'	278	3	280	6	355*310*310	48
	13'	330	5	338	10	365*365*360	80